



COPY OF PAPERS
ORIGINALLY FILED

#13/3-20-02
2222
Date

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor: Rich Fogal and Michael B. Ball

Serial No.: 09/422,887

Filed: October 21, 1999

For: ANGULARLY OFFSET STACKED DIE MULTICHIP
DEVICE AND METHOD OF MANUFACTURE

§ Group Art Unit: 2822
§
§ Examiner: J. Brophy
§
§ Atty. Docket: 95-0134.05
§
§
§
§

RECEIVED
MAR - 7 2002
1C 2800 MAIL ROOM

FORMAL DRAWINGS TRANSMITTAL

Attn: Office of Official Draftsperson/Drawing Review Branch

Commissioner for Patents

Washington, D.C. 20231

Certificate of Mailing (37 C.F.R. § 1.8)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on the date below:

2/19/02 Date
Susan Ferguson Signature

Dear Sir:

Applicants herein submit substitute formal drawings in triplicate in addition to a redlined copy. A copy of these drawings have been sent to the Examiner.

Approved
Q.B.
6/18/02

2/19/02

Respectfully submitted,

Charles Brantley

Charles Brantley
Registration No. 38,086
Micron Technology, Inc.
8000 S. Federal Way
Boise, ID 83716-9632
(208) 368-4557

Attorney for Applicants